

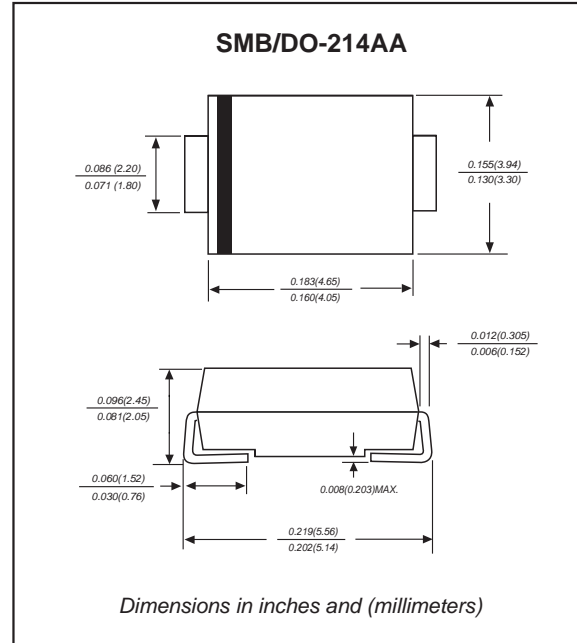
Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance
- Low profile surface mounted application in order to optimize board space
- Low power loss, high efficiency
- High current capability, low forward voltage drop
- High surge capability
- Guardring for overvoltage protection
- Ultra high-speed switching
- Lead-free parts meet RoHS requirements
- Halogen-free

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AA / SMB
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

Package outline



Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	MBRS240LT3G	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	40	Volts
Maximum RMS voltage	V_{RMS}	28	Volts
Maximum continuous reverse voltage	V_R	40	Volts
Maximum average forward rectified current	I_O	2.0	A
Non-repetitive peak forward surge current 8.3ms single half sine-wave	I_{FSM}	50	A
Typical diode junction capacitance (Note 1)	C_J	160	pF
Operating junction temperature range	T_J	-55 to +125	$^\circ\text{C}$
Storage temperature range	T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	MBRS240LT3G	UNITS
Maximum instantaneous forward voltage at $I_F=2.0\text{A}$	V_F	0.43	Volts
Maximum reverse leakage current at rated V_R	I_R	1.0 50	mA mA
			$T_J=25^\circ\text{C}$ $T_J=100^\circ\text{C}$

Thermal characteristics

PARAMETER	SYMBOLS	MBRS240LT3G	UNITS
Typical thermal resistance junction to ambient (Note 2)	$R_{\theta JA}$	78	$^\circ\text{C} / \text{W}$
Typical thermal resistance junction to case (Note 2)	$R_{\theta JC}$	18	$^\circ\text{C} / \text{W}$

Notes 1: Measured at 1 MHz and applied reverse voltage of 4.0 VDC
 2: Mounted on FR-4 PCB copper, minimum recommended pad layout

Rating and characteristic curves

FIG.1-TYPICAL FORWARD CHARACTERISTICS

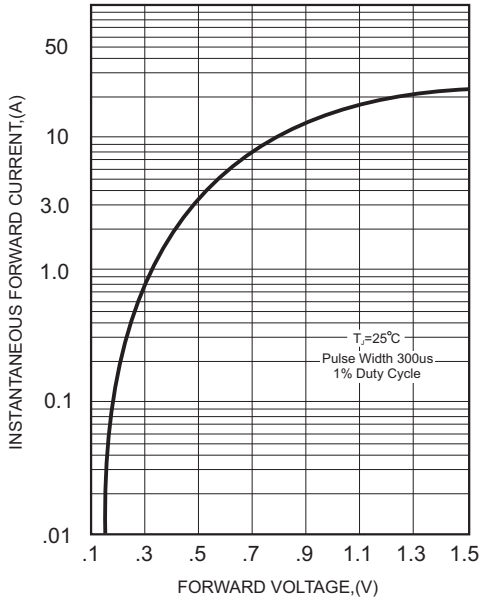


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

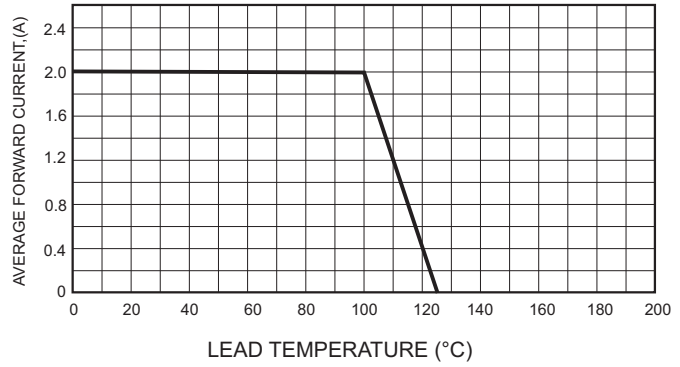


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

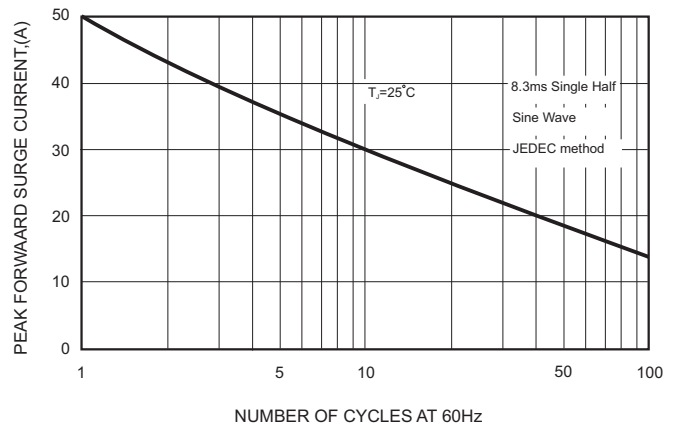


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

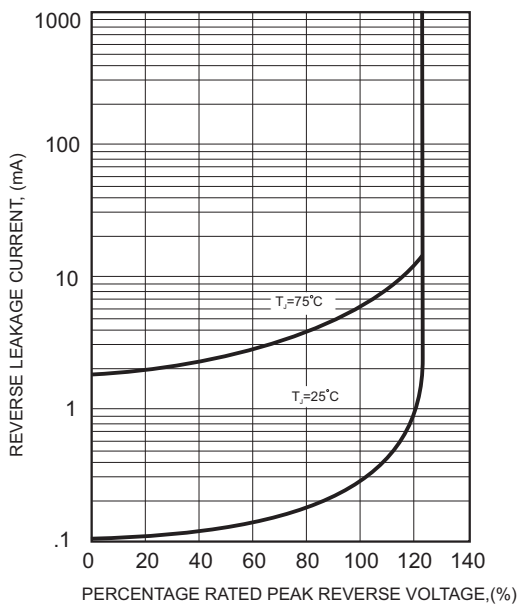
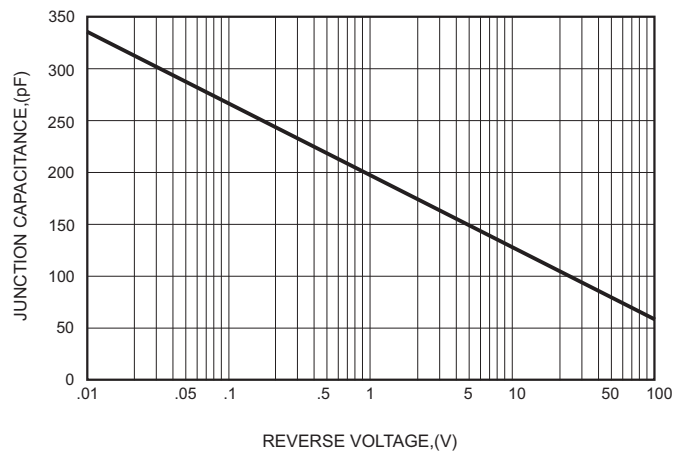


FIG.5-TYPICAL JUNCTION CAPACITANCE



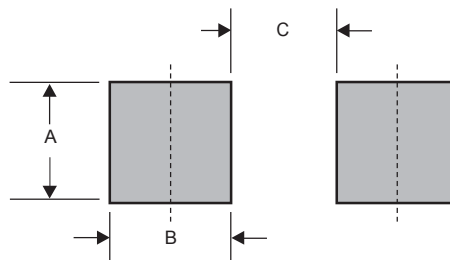
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
MBRS240LT3G	2BL4

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMB	0.078 (2.00)	0.059 (1.50)	0.110 (2.80)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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